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ESD

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DTA114EE(MS)

Product specification





Digital Transistor (Built-in Resistors) PNP Silicon Surface Mount Transistor

FEATURES

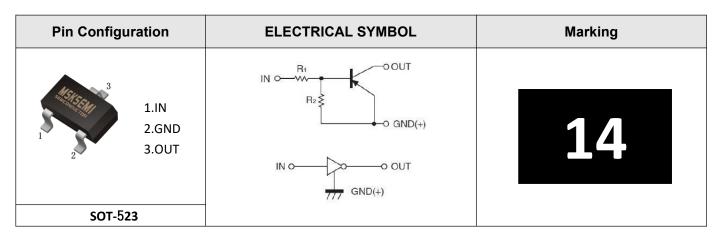
- Built-in resistors enable the configuration of a inverter circuit without connecting external input resistors.
- The bias resistors consist of thin-film resistors with complete isolation to allow positive biasing of the input. They also have the advantage of almost completely eliminating parasitic effects.
- Only the on/off conditions need to be set for operation, making device design easy.
- RoHS Compliant
- Green EMC
- Matte Tin(Sn) Lead Finish
- Weight: approx. 0.002g

Absolute Maximum Ratings (TA = 25°C unless otherwise noted)

Symbol	Parameter	Value	Units
Vcc	Supply Voltage	-50	V
Vin	Input Voltage	-40 ~ +10	V
lo	Output Current	-50	mA
Ісм	Peak Collector Current	- 100	mA
PD	Power Dissipation	150	mW
TJ	Junction to Ambient	150	°C
Тѕтс	Storage Temperature Range	-55 to +150	°C

These ratings are limiting values above which the serviceability of the device may be impaired

Reference News



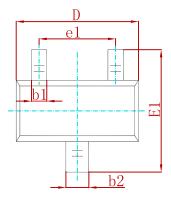


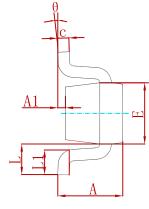
Electrical Characteristics (T_A = 25, C unless otherwise noted)

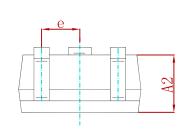
Devementer	ter Symbol Test Condition	Test Candition	Limits			
Parameter		Min	Тур	Max	Unit	
	VI(off)	Vcc= -5V, Io= -100uA	-0.5			V
Input Voltage	VI(on)	Vo= -0.3V, Io= -10mA			-3	V
Output Voltage	VO(on)	lo / lı = -10mA/-0.5mA			-0.3	V
Input Current	lı	V _I = -5V			-0.88	mA
Output Current	IO(off)	$V_{CC} = -50V, V_{I} = 0$			-0.5	uA
DC Current Gain	Gı	$V_{O} = -5V, I_{O} = -5mA$	30			
Input Resistance	R1		7	10	13	ΚΩ
Resistance Ratio	R2 /R1		0.8	1	1.2	
Transition Frequency	fт	Vo = -10V, lo = -5mA f=100MHz		250		MHz



PACKAGE MECHANICAL DATA

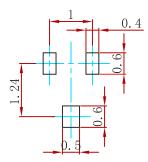






Symphol	Dimensions In Millimeters		Dimensions In Inches		
Symbol	Min.	Max.	Min.	Max.	
A	0.700	0.900	0.028	0.035	
A1	0.000	0.100	0.000	0.004	
A2	0.700	0.800	0.028	0.031	
b1	0.150	0.250	0.006	0.010	
b2	0.250	0.350	0.010	0.014	
С	0.100	0.200	0.004	0.008	
D	1.500	1.700	0.059	0.067	
E	0.700	0.900	0.028	0.035	
E1	1.450	1.750	0.057	0.069	
е	0.500	TYP.	0.020	TYP.	
e1	0.900	1.100	0.035	0.043	
L	0.400	REF.	0.016	REF.	
L1	0.260	0.460	0.010	0.018	
θ	0°	8°	0°	8°	

Suggested Pad Layout



Note:

1.Controlling dimension:in millimeters.

2.General tolerance:±0.05mm.

3. The pad layout is for reference purposes only.

REEL SPECIFICATION

P/N	PKG	QTY
DTA114EE(MS)	SOT-523	3000



DTA114EE(MS)

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